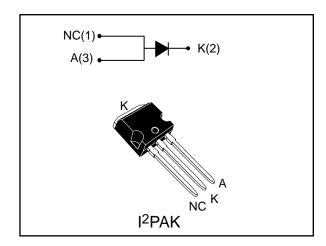
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STPSC10C065-Y

Automotive 650 V power Schottky silicon carbide diode

Datasheet - production data



Features



- AEC-Q101 qualified
- No reverse recovery charge in application current range
- Switching behavior independent of temperature
- Recommended to PFC applications
- PPAP capable
- ECOPACK[®]2 compliant component

Description

The SiC diode is an ultra high performance power Schottky diode. It is manufactured using a silicon carbide substrate. The wide band gap material allows the design of a Schottky diode structure with a 650 V rating. Due to the Schottky construction, no recovery is shown at turn-off and ringing patterns are negligible. The minimal capacitive turn-off behavior is independent of temperature.

Especially suited for use in PFC applications, this ST SiC diode will boost performance in hard switching conditions.

Table 1: Device summary

Symbol	Value
I _{F(AV)}	10 A
Vrrm	650 V
T _j (max.)	175 °C

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Table 2: Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Parameter			Unit
V _{RRM}	Repetitive peak reverse voltage T _j from -40 °C to 175 °C		650	V
I _{F(RMS)}	Forward rms current		22	Α
I _{F(AV)}	Average forward current	$T_C = 120 ^{\circ}C^{(1)}$, DC current	10	Α
	Surge non repetitive forward current	t _p = 10 ms sinusoidal, T _c = 25 °C	85	
I _{FSM}		$t_p = 10 \text{ ms sinusoidal, } T_c = 150 ^{\circ}\text{C}$	75	Α
	Carron	$t_p = 10 \ \mu s \ square, T_c = 25 \ ^{\circ}C$	500	
T _{stg}	Storage temperature range	-55 to +175	°C	
Tj	Operating junction temperature ⁽²⁾	-40 to +175	°C	

Notes:

Table 3: Thermal parameters

Symbol	Symbol Parameter		Value		
Symbol	Parameter	Тур.	Max.	Unit	
R _{th(j-c)}	Junction to case	1.3	2.0	°C/W	

Table 4: Static electrical characteristics

	Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
	ı (1)	Doverse leekens overent	T _j = 25 °C	\/ \/	-	9	100	
	I _R ⁽¹⁾	Reverse leakage current	T _j = 150 °C	$V_R = V_{RRM}$	-	85	425	μA
Ī	V _F ⁽²⁾	Forward voltage drop	T _j = 25 °C	, IF = 10 A	-	1.56	1.75	W
			T _j = 150 °C		-	1.98	2.50	V

Notes:

 $^{(1)}\text{Pulse}$ test: t_p = 5 ms, δ < 2%

 $^{(2)}$ Pulse test: t_p = 500 μ s, δ < 2%

To evaluate the conduction losses, use the following equation:

 $P = 1.35 \text{ x } I_{F(AV)} + 0.12 \text{ x } I_{F^2(RMS)}$

Table 5: Dynamic electrical characteristics

	Symbol	Parameter	Test conditions	Тур.	Unit		
	Q _{Cj} ⁽¹⁾	Total capacitive charge	V _R = 400 V	26.4	nC		
Ī			$V_R = 0 \text{ V}, T_c = 25 \text{ °C}, F = 1 \text{ MHz}$	480	, F		
	Cj	Total capacitance	V _R = 400 V, T _c = 25 °C, F = 1 MHz	47	pF		

Notes: $^{(1)}$ Most accurate value for the capacitive charge: $Q_{cj}(V_R) = \int_0^{V_R} C_j(V) dV$



 $[\]ensuremath{^{(1)}}\mbox{Value}$ based on $R_{th(j\text{-}c)}$ max.

 $^{^{(2)}(}dP_{tot}/dT_j) < (1/R_{th(j\text{-}a)}) \ condition \ to \ avoid \ thermal \ runaway \ for \ a \ diode \ on \ its \ own \ heatsink.$

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Characteristics (curves) 1.1

Figure 1: Forward voltage drop versus forward current (typical values, low level) 20 Pulse test : t_p = 500 µs 16 $T_a = 100 \, ^{\circ}C$ 12

current (typical values, high level) 100 Pulse test : t_p = 500 µs 80 60 40 $T_a = 100 \,^{\circ}C$ T_a = 150 °C 20 $V_F(V)$ 0 0

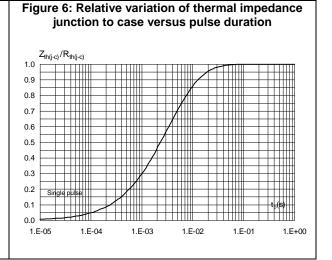
Figure 2: Forward voltage drop versus forward

T. = 150 °C -T_a = 175 °C $V_F(V)$ T_a = -40 °C 0.0 2.0 2.5 0.5 1.0 1.5 3.0

Figure 3: Reverse leakage current versus reverse voltage applied (typical values) $I_R(\mu A)$ 1.E+03 1.E+02 1.E+01 1.E+00 1.E-01 1.E-02 1.E-03 1.E-04 100 150 200 250 300 350 400 450 500 550 600 650

Figure 4: Peak forward current versus case temperature $I_M(A)$ 80 $\delta = 0.1$ 70 60 $\delta = 0.3$ 40 δ = 0.5 30 20 $\delta = 0.7$ 10 $T_C(^{\circ}C)$ 0 175

Figure 5: Junction capacitance versus reverse voltage applied (typical values) $C_i(pF)$ 500 400 300 100 0 0.1 1.0 10.0 100.0 1000.0



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Figure 7: Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)

I_{FSM}(A)

1.E+03

1.E+01

1.E+01

1.E-05

1.E-04

1.E-03

1.E-02

voltage applied (typical values)

Q_{Qi}(nC)

25

20

15

10

5

0

0

50

100

150

200

250

300

350

400

Figure 8: Total capacitive charges versus reverse

STPSC10C065-Y Package information

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

2.1 I²PAK package information

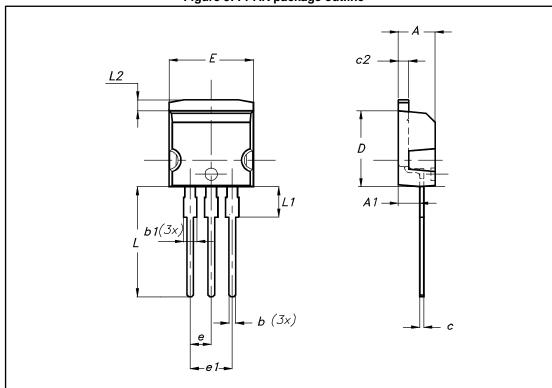


Figure 9: I²PAK package outline

Table 6: I²PAK package mechanical data

	Dimensions						
Ref.	Ref. Millimeters				Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.	
А	4.40		4.60	0.173		0.181	
A1	2.40		2.72	0.094		0.107	
b	0.61		0.88	0.024		0.035	
b1	1.14		1.70	0.044		0.067	
С	0.49		0.70	0.019		0.028	
c2	1.23		1.32	0.048		0.052	
D	8.95		9.35	0.352		0.368	
е	2.40		2.70	0.094		0.106	
e1	4.95		5.15	0.195		0.203	
Е	10		10.40	0.394		0.409	
L	13		14	0.512		0.551	
L1	3.50		3.93	0.138		0.155	
L2	1.27		1.40	0.050		0.055	

STPSC10C065-Y Ordering information

3 Ordering information

Table 7: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPSC10C065RY	PSC10C065RY	I ² PAK	1.5 g	50	Tube

4 Revision history

Table 8: Document revision history

Date	Revision	Changes
16-Feb-2018	1	First issue.

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